

LaserCleave™- SSP

The LaserCleave™ range from world leading laser processing tool supplier and creator of the original LaserCleave™ process for optical fiber termination.

The LaserCleave™ SSP, Provides the optimum pre-polish cleave of fiber and epoxy for **Single Step Polishing** of simplex optical interconnect termination. OpTek's proprietary LaserCleave™ process cuts close to the ferrule end face eliminating all but one polish step with a finishing film, saving on materials, time and equipment while improving your first pass yield.



System Performance

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|--------------------------|---|
| ▪ Process speed: | Typically >500UPH |
| ▪ Small protrusion: | Typically <30µm(LC) <35µm(SC) |
| ▪ Single step polish: | Eliminate unnecessary polishing. |
| | Minimize polishing Materials and equipment |
| ▪ Polish friendly shape: | Rounded end, no sharp corner or edges. |
| ▪ Enhanced features: | Smooth finish, non-contact process. |
| ▪ Reliable: | No core cracks or cleaving back into ferrule |
| ▪ Flexibility: | Interchangeable port for different connectors |
| ▪ Ergonomic: | User friendly design and operation. |



System Requirements

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| ▪ Power: | Single phase, 1.7kVA |
| ▪ Cooling: | Air cooled: Water cooling option |
| ▪ Vision: | Integrated vision systems |
| ▪ Shards: | Large capacity collection >1M fiber shards |
| ▪ Size: | Bench top (W756xD505xH245mm) |
| ▪ Weight: | 35kg (bench top model) |

